

<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>		Application No.	10/822,424
		Filing Date	April 12, 2004
		First Named Inventor	Bulent M. Basol
		Art Unit	<del>1742</del> 1795
(Multiple sheets used when necessary)		Examiner	Zulmariam Mendez
SHEET 1 OF 2		Attorney Docket No.	NVLUS.029CP1(5296)

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Examiner Initials	Cite No.	Document Number Number - Kind Code (if known) Example: 1,234,567 B1	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
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/Z.M./	4	DE 2008664	09-09-1971	Jostan		
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**NON PATENT LITERATURE DOCUMENTS**

Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>1</sup>
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Examiner Signature	/Zulmariam Mendez/	Date Considered	10/28/2007
*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

T<sup>1</sup> - Place a check mark in this area when an English language Translation is attached.

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